

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A circuit board manufacturing method, comprising:

forming a transfer chip, the forming of the transfer chip including:

forming a wiring above a first ~~substrate,~~substrate and

~~forming~~ a plurality of first pad electrodes so as to be connected to the wiring and so as to be included in the transfer chip, and

joining the transfer chip with a member such that the plurality of first pad electrodes contact the member.

2. (Previously Presented) The circuit board manufacturing method according to claim 1, each of the plurality of first pad electrodes having a plurality of first portions, one of the plurality of first portions being located a greatest distance away from a bottom of the transfer chip, and the greatest distance substantially coinciding with the plurality of first pad electrodes.

3. (Currently Amended) The circuit board manufacturing method according to claim 1, further comprising:

forming the member, the forming of the member including:

forming a second substrate, and

forming electrical circuit wiring above the second ~~substrate,~~

~~and~~substrate and

~~forming~~ a plurality of second pad electrodes so as to be connected to the electrical circuit wiring and arranged in a transfer target region, the second pad electrodes being respectively associated with the plurality of first pad electrodes provided on the transfer chip.

4. (Previously Presented) The circuit board manufacturing method according to claim 2, further comprising:

adjusting a distance of at least one of the plurality of first portions of each of the first pad electrodes from the bottom of the first substrate by adding distance adjusting films when forming the transfer chip.

5. (Previously Presented) The circuit board manufacturing method according to claim 3, forming the plurality of second pad electrodes so as to cover the electrical circuit wiring, each of the plurality of second pad electrodes having a plurality of second portions, one of the plurality of second portions being located a greatest distance away from a bottom of the second substrate, the greatest distance substantially coinciding with the plurality of second pad electrodes.

6. (Previously Presented) The circuit board manufacturing method according to claim 5, further comprising:

adjusting a distance of at least one of the plurality of second portions of each of the second pad electrodes from the bottom of the second substrate by adding distance adjusting films when forming the member.

7. (Previously Presented) The circuit board manufacturing method according to claim 1, the plurality of first pad electrodes having a film structure that is the same as a film structure in regions associated with a greatest distance of a plurality of first portions of each of the first pad electrodes from a bottom of the transfer chip.

8. (Previously Presented) The circuit board manufacturing method according to claim 3, the plurality of second pad electrodes having a film structure that is the same as a film structure in regions associated with a greatest distance of a plurality of second portions of each of the second pad electrodes from a bottom of the second substrate.

9. (Previously Presented) The circuit board manufacturing method according to claim 1, further comprising:

connecting one first portion of a plurality of first portions of one first pad electrode of the plurality of first pad electrodes to one second portion of a plurality of second portions of one second pad electrode of a plurality of second pad electrodes; and

connecting one first portion of the plurality of first portions of another first pad electrode of the plurality of first pad electrodes to one second portion of the plurality of second portions of another second pad electrode of the plurality of second pad electrodes,

a distance between a bottom of the transfer chip and a bottom of the second substrate through the one first pad electrode and the one second pad electrode coinciding with a distance through the another first pad and the another second pad electrode.

10. (Previously Presented) The circuit board manufacturing method according to claim 3, the joining of the transfer chip with the member including forming adhesive layers between the first pad electrodes provided on the transfer chip and the second pad electrodes provided on the second substrate.

11. (Previously Presented) The circuit board manufacturing method according to claim 1, the forming of the transfer chip including forming an ablation layer between the first substrate and the transfer chip, the ablation layer having a characteristic such that the adhesiveness with respect to the transfer chip is weakened due to a change of state in response to application of energy.

12. (Withdrawn) A transfer chip serving as a transfer unit manufactured by the method of claim 3.

13. (Withdrawn) An electro-optical device manufactured using a circuit board manufactured by the manufacturing method as set forth in claim 1.

14. (Withdrawn) An electronic apparatus, comprising:
the electro-optical device as set forth in claim 13 usable as a display unit.